



## Material Content Data Sheet



Sales Product Name	TLE4961-4M			Issued		28. October 2019		
MA#	MA005402993							
Package	PG-SOT23-3-15			Weight*		9.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.350	3.56	3.56	35595	35595
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		73	
	non noble metal	titanium	7440-32-6	0.004	0.04		367	
	non noble metal	chromium	7440-47-3	0.011	0.11		1101	
	non noble metal	copper	7440-50-8	3.590	36.56	36.72	365591	367132
wire	noble metal	gold	7440-57-5	0.019	0.19	0.19	1891	1891
encapsulation	organic material	carbon black	1333-86-4	0.054	0.55		5463	
	plastics	epoxy resin	-	1.153	11.75		117454	
	inorganic material	silicondioxide	60676-86-0	4.157	42.33	54.63	423382	546299
leadfinish	non noble metal	tin	7440-31-5	0.150	1.52	1.52	15240	15240
plating	noble metal	silver	7440-22-4	0.149	1.51	1.51	15132	15132
glue	plastics	epoxy resin	-	0.032	0.33		3274	
	noble metal	silver	7440-22-4	0.152	1.54	1.87	15437	18711
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com